

**Amendments to the CLAIMS**

1-48. (Cancelled)

49. (New) A light emitting device package, comprising:  
a base having an entire top surface that is flat;  
a light emitting device directly on the flat top surface of the base;  
an electrical circuit layer including at least one end portion placed adjacent to the light emitting device;  
an electrode layer disposed above a tip portion of the at least one end portion of the electrical circuit layer; and  
a lens covering the light emitting device and the electrode layer.

50. (New) The light emitting device package of claim 49, wherein an entire bottom surface of the electrode layer is in contact with the electrical circuit layer.

51. (New) The light emitting device package of claim 49, wherein the electrode layer is separated from the light emitting device and does not directly contact the light emitting device.

52. (New) The light emitting device package of claim 49, wherein the lens is a molding which completely fills up any space between the light emitting device and the electrode layer.

53. (New) The light emitting device package of claim 49, wherein the entire electrode layer is encapsulated by the lens.

54. (New) The light emitting device package of claim 49, further comprising an insulating layer between the electrical circuit layer and the base.

55. (New) The light emitting device package of claim 49, wherein a top surface of the electrode layer is plated.

56. (New) The light emitting device package of claim 49, wherein the base is made of a metal.

57. (New) The light emitting device package of claim 49, further comprising a heat sink disposed on a bottom surface of the base.

58. (New) The light emitting device package of claim 49, wherein the base has a hole.

59. (New) The light emitting device package of claim 58, wherein the hole is in contact with a heat sink disposed on a bottom surface of the base.

60. (New) The light emitting device package of claim 49, further comprising a plating layer on the electrode layer.

61. (New) A light emitting device comprising:

at least one light emitting package, each including:

a base having an entire top surface that is flat,

a light emitting unit directly on the flat top surface of the base,

an electrical circuit layer including at least one end portion placed adjacent to the light emitting unit,

an electrode layer disposed above a tip portion of the at least one end portion of the electrical circuit layer, and

a lens covering the light emitting unit and the electrode layer.

62. (New) The light emitting device of claim 61, wherein the light emitting device includes more than one said light emitting package.

63. (New) The light emitting device of claim 61, wherein an entire bottom surface of the electrode layer is in contact with the electrical circuit layer.

64. (New) The light emitting device of claim 61, wherein the electrode layer is separated from the light emitting unit and does not directly contact the light emitting unit.

65. (New) The light emitting device of claim 61, wherein the lens is a molding which completely fills up any space between the light emitting unit and the electrode layer.

66. (New) The light emitting device of claim 61, wherein the entire electrode layer is encapsulated by the lens.

67. (New) The light emitting device of claim 61, wherein each of the at least one light emitting package further comprises a heat sink disposed on a bottom surface of the base.

68. (New) The light emitting device of claim 61, wherein the base has a hole.

69. (New) The light emitting device of claim 68, wherein the hole is in contact with a heat sink disposed on a bottom surface of the base.

70. (New) The light emitting device of claim 61, wherein each of the at least one light emitting package further comprises a plating layer on the electrode layer.